



## AT A GLANCE

Ultra-fast, low-loss and flexible electrical interconnects for opto-electrical packaging.

### Features

Polymer embedded electrical coplanar waveguides.

- Bandwidth > 200GHz
- Customized design
- mm to cm scale

### Applications

High speed flexible electrical chip to chip interconnect:

- Driver-to-LD
- PD-to-TIA

### Technical Background

Ultra-fast, low-loss and flexible electrical coplanar waveguides for interconnecting drivers to laser and photo detectors to transimpedance amplifiers (TIAs) with bandwidths exceeding 200 GHz.

Fabricated on wafer scale.

Customized design available.

## References

International R&D projects

PHOENICS

POETICS

POLYNICES

QSNP

Qu-Test / Qu-Pilot

SPRINTER

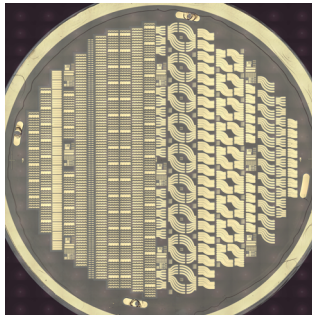
TERA 6G

TERAMEASURE

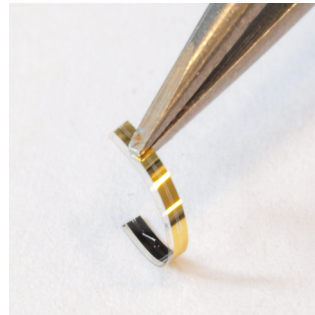
TERAWAY

(funded by EU commission)

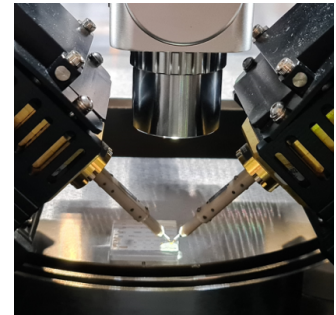
## Characteristics



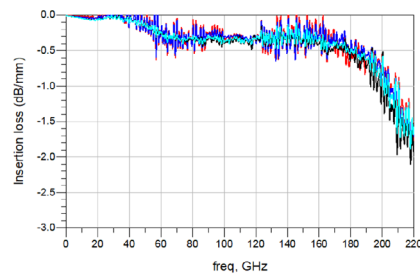
*Fabrication on wafer scale,  
customized design*



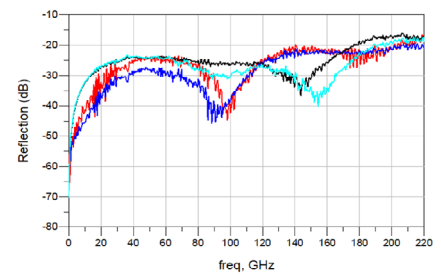
*Flexible electrical interconnects*



*RF characterization set-up*

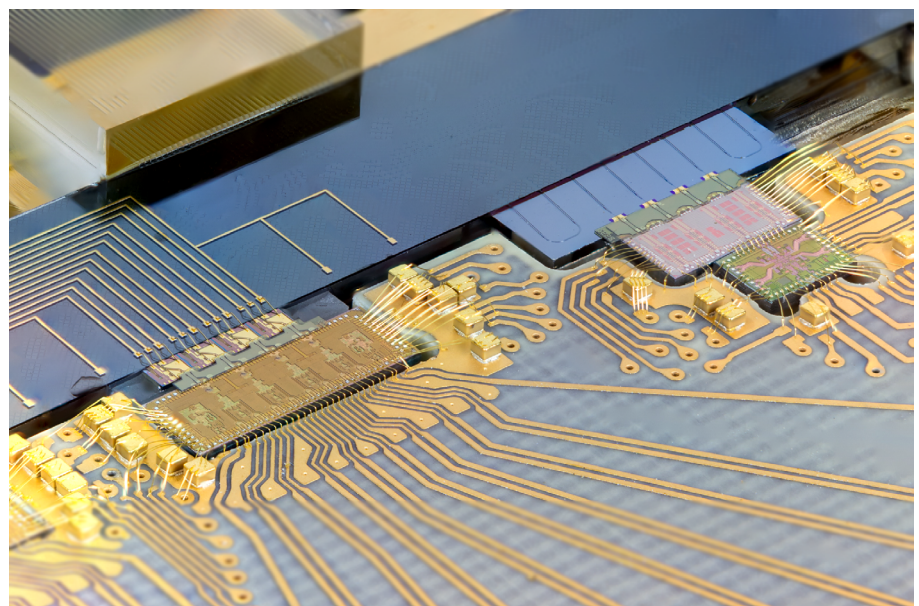


*Transmission: >> 200 GHz*



*Reflection: <-20 dB*

## Applications



*1.6 Tb/s optical transceiver with FlexLines for intra datacenter connectivity (EU POETICS).*

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